

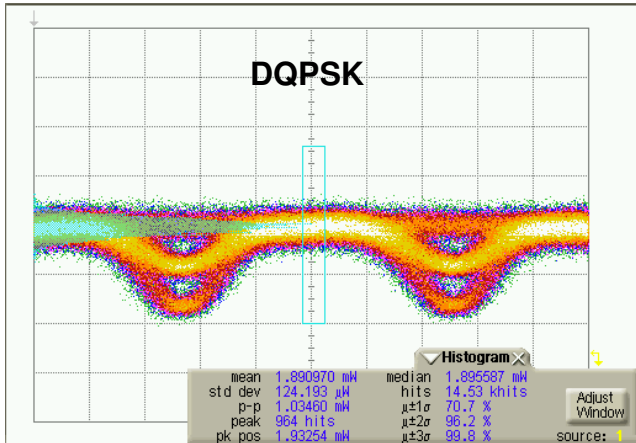
40 & 100 Gb/s 8Vpp Optical Modulator Driver



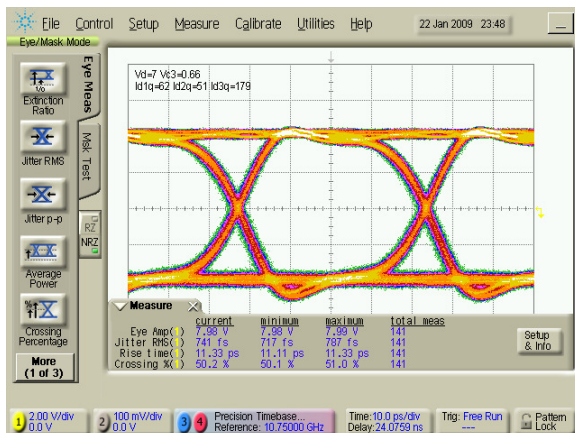
Measured Performance

Bias conditions: $V_{d1,2,3} = 7\text{ V}$, $I_{dq} = 310\text{ mA}$,
 $V_{c1,2,3} = 0.7, 0.7, 0.8\text{ V}$ Typical

22 Gb/s, 0.48 Vpp Input, $V_{out} = 7.2\text{ Vpp}$.



$V_{in} = 0.5\text{ Vpp}$, $V_{out} = 8\text{ Vpp}$, 21.5 Gbps, PRBS 2³¹-1



Key Features

- 40 & 100 Gb/s Performance
- Single Ended Input and Output
- Adjustable Output Amplitude, 3 Vpp – 9 Vpp
- Low Additive RMS Jitter, 400 fsec
- High Output Drive, 8Vpp with 0.4 Vpp Input
- Gain, 32 dB at 20 GHz
- Low DC Power Dissipation, 1.7 W for $V_{out} = 8\text{ Vpp}$ at $V_d=6\text{ V}$
- Rise and Fall Times <12 psec
- Hot Pluggable
- Package Size: 14.4 x 7 x 2 mm

Primary Applications

- 40 GB/s Optical Market: DQPSK (2x)
- 100 GB/s Optical Market: DP-QPSK (4x)

Product Description

The TriQuint TGA4943-SL is a three stage optical modulator driver amplifier designed to operate at frequencies that target both the 40 and 100 Gb/s optical market using an 14.4 x 7 x 2 mm surface mount system in package (SIP).

The TGA4943-SL consists of three high performance wideband amplifiers assembled in a surface mount package combined with a minimum of off-chip components. A single TGA4943-SL placed between the MUX and Optical Modulator provides OEMs with a modulator driver surface mount solution.

The TGA4943-SL provides Metro and Long Haul designers with system critical features such as: low power dissipation, low rail ripple, high voltage drive capability (3 Vpp amplitude adjustable up to 9 Vpp), low output jitter, and low input drive sensitivity (0.4 Vpp – 1 Vpp at $V_{out} = 8\text{ Vpp}$).

The TGA4943-SL is lead-free and RoHS compliant. Evaluation boards are available upon request.

Table I
Absolute Maximum Ratings 1/

Symbol	Parameter	Value	Notes
Vd1, Vd2, Vd3	Drain Voltage	9 V	<u>2/</u> <u>3/</u> <u>4/</u> <u>5/</u>
Vd1-Vg1, Vd2-Vg2, Vd3-Vg3	Drain to Gate Voltage	10 V, 13 V, 13 V	<u>2/</u> <u>3/</u> <u>4/</u> <u>5/</u>
Vg1, Vg2, Vg3	Gate Voltage Range	-5 to 0 V	
Vc1, Vc2, Vc3	Control Voltage Range	(Vd-7) to +5.5 V	<u>3/</u> <u>4/</u> <u>5/</u>
Id1, Id2	Drain Current	80, 135 mA	<u>2/</u>
Id3	Drain Current	270 mA	<u>2/</u>
Ig1, Ig2, Ig3	Gate Current Range	-15 to 21 mA, -30 to 21 mA, -30 to 21 mA	<u>5/</u>
Ic1, Ic2, Ic3	Control Current Range	-15 to 21 mA	<u>5/</u>
Vin_pp	Peak-Peak Input Voltage	7 V	
Pin	Input Continuous Wave Power	24 dBm	<u>2/</u>
Pd	Max Power Dissipation	3.05	<u>6/</u>
Tch	Maximum Channel Temperature	200 °C	

- 1/ These ratings represent the maximum operable values for this device. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device and / or affect device lifetime. These are stress ratings only, and functional operation of the device at these conditions is not implied.
- 2/ Combinations of supply voltage, supply current, input power, and output power shall not exceed the maximum power dissipation listed in Table IV.
- 3/ Assure $Vd1 - (Vc1 - Vg1) - Id1 * 50 \leq 6.5$ V,
 Assure $Vd2 - (Vc2 - 0.34 * Vg2) - Id2 * 50 \leq 6.5$ V,
 Assure $Vd3 - (Vc3 - 0.34 * Vg3) \leq 6.5$ V,
- 4/ Assure $Vd - Vc \geq -0.5$.
- 5/ HOT PLUGGABLE: Comply with voltage and currents outlined in Max Ratings Table.
- 6/ Maximum Power Dissipation is based upon Baseplate temperature of 80 °C and Channel Temperature of 200 °C, using the thermal resistance published in Table IV.

Table II
Recommended Operating Conditions
21.5 Gbps Operation

Output Voltage (Vpp)	Drain Voltage: Vd1, Vd2, Vd3 (V)	Quiescent Drain Current: Idq1, Idq2, Idq3 (mA)	Under RF Drive Drain Current: Id1+ Id2 + Id3 (mA)	Control Voltage: Vc1, Vc2, Vc3 (V)	Gate Voltage: Vg1, Vg2, Vg3 (V)*	Pdiss (W)
3.6	5	40, 30, 84	198	0.7, 0.7, -0.23	-0.56, -1.89, -1.34	0.96
4	5	40, 30, 100	207	0.7, 0.7, -0.01	-0.56, -1.89, -1.25	1.00
5	5	40, 30, 133	230	0.7, 0.7, 0.23	-0.56, -1.89, -1.09	1.09
6	5	40, 30, 160	254	0.7, 0.7, 0.42	-0.56, -1.89, -0.97	1.18
4	6	51, 51, 63	233	0.7, 0.7, -0.06	-0.51, -1.68, -1.53	1.32
5	6	51, 51, 100	257	0.7, 0.7, 0.14	-0.51, -1.68, -1.30	1.42
6	6	51, 51, 135	281	0.7, 0.7, 0.36	-0.51, -1.68, -1.11	1.51
7	6	51, 51, 167	305	0.7, 0.7, 0.59	-0.51, -1.68, -0.95	1.59
8	6	51, 51, 201	330	0.7, 0.7, 0.86	-0.51, -1.68, -0.78	1.66
6	7	62, 50, 98	302	0.7, 0.7, 0.24	-0.47, -1.74, -1.34	2.03
7	7	62, 50, 144	326	0.7, 0.7, 0.45	-0.47, -1.74, -1.09	2.16
8	7	62, 50, 179	348	0.7, 0.7, 0.66	-0.47, -1.74, -0.92	2.28
9	7	62, 50, 223	373	0.7, 0.7, 0.91	-0.47, -1.74, -0.69	2.4

* Gate and control voltages should be adjusted to reach target drain currents and optimal eye performance and may vary from above voltages.

**Table III
RF Characterization Table**

Bias: Vd = 7 V, Idq=310 mA, Vc1, Vc2 = +0.7 V, Vc3 = +0.8 V, typical

Small Signal Characteristics*

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOMINAL	MAX	UNITS
Gain	Small Signal Gain	f = 0.1 - 18 GHz	30	32	-	dB
		f = 18.1 - 29 GHz	27.5	30	-	
		f = 29.1 - 32 GHz	25	28	-	
		f = 32.1 - 36 GHz	21	25	-	
		f = 36.1 - 40 GHz	17	21	-	
IRL	Input Return Loss	f = 0.1 - 30 GHz	10	15	-	dB
		f = 30.1 - 34 GHz	5	8	-	
		f = 34.1 - 40 GHz	3	6	-	
ORL	Output Return Loss	f = 0.1 - 22 GHz	10	15	-	dB
		f = 22.1 - 30 GHz	6.5	8	-	
		f = 30.1 - 40 GHz	3	6	-	
BW	3 dB Bandwidth	f(x) - f(1 GHz) = 3 dB x = freq of 3 dB BW	-	27	-	GHz

* NOTE: data includes DC block on input and external bias tee on output

Table III - Cont.
RF Characterization Table

Bias: Vd = 7 V, Idq ~ 300 mA, Vc1, Vc2 = 0.6 V, Vc3 = 0.8 V, typical

Electrical Eye Test Conditions: Vin = 0.5 Vpp, PRBS 2³¹-1, 21.5 Gbps, Crossing = 50% +/- 2%

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	NOMINAL	MAX	UNITS
Vout_Max	Maximum Eye Amplitude	500 mVpp Input	-	10	-	Vpp
Tr	Risetime	8 Vpp Output	-	12	14	psec
Tf	Falltime	8 Vpp Output		12		psec
SNR	Signal to Noise Ratio	8 Vpp Output	14.5	20		dB
Eye Opening	<u>1/</u>	8 Vpp Output		85		%
Jrms_Add	Additive Jitter <u>2/</u>	8 Vpp Output		500	850	fsec
Jpp	P-P Jitter	8 Vpp Output		6	7.8	psec
Id	Total Drain Current	8 Vpp Output	-	350	-	mA

1/ Eye Opening defined as: [Eye Height (Vpp)/Eye Amplitude (Vpp)] *100

2/ Additive Jitter defined as: Sqrt [(Total RMS Jitter)² – (Input RMS Jitter)²]

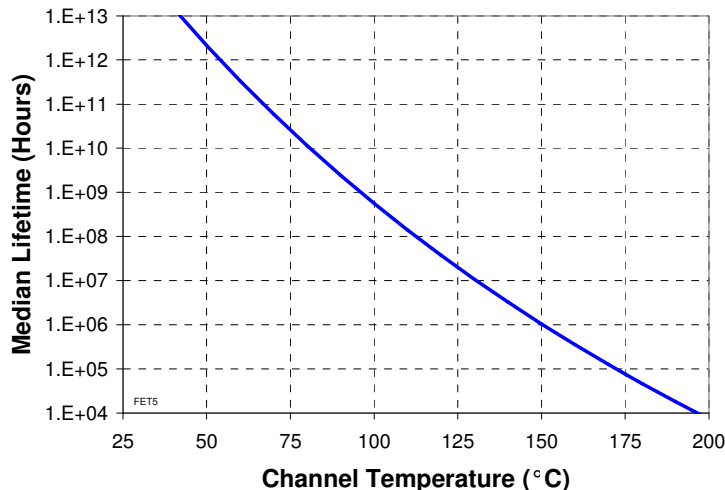
Table IV
Power Dissipation and Thermal Properties

Parameter	Test Conditions	Value	Notes
Thermal Resistance, θ_{jc}	Vd = 7 V Idq_tot = 300 mA Idq3=190 mA Pd_stage3 = 1.33 W Tbaseplate = 85 °C	$\theta_{jc} = 39.4 \text{ }^{\circ}\text{C/W}$ Tchannel = 137.4 °C Tm = 4.3 E+6 Hrs	<u>1/</u> , <u>2/</u>
Thermal Resistance, θ_{jc} Under RF Drive	Vout = 8 Vpp, Vd = 7V Id3 = 190 mA Pd_stage3 =1.17 W Tbaseplate = 85 °C	$\theta_{jc} = 39.4 \text{ }^{\circ}\text{C/W}$ Tchannel = 131 °C Tm = 9.2 E+6 Hrs	
Storage Temperature		-65 to 150 °C	

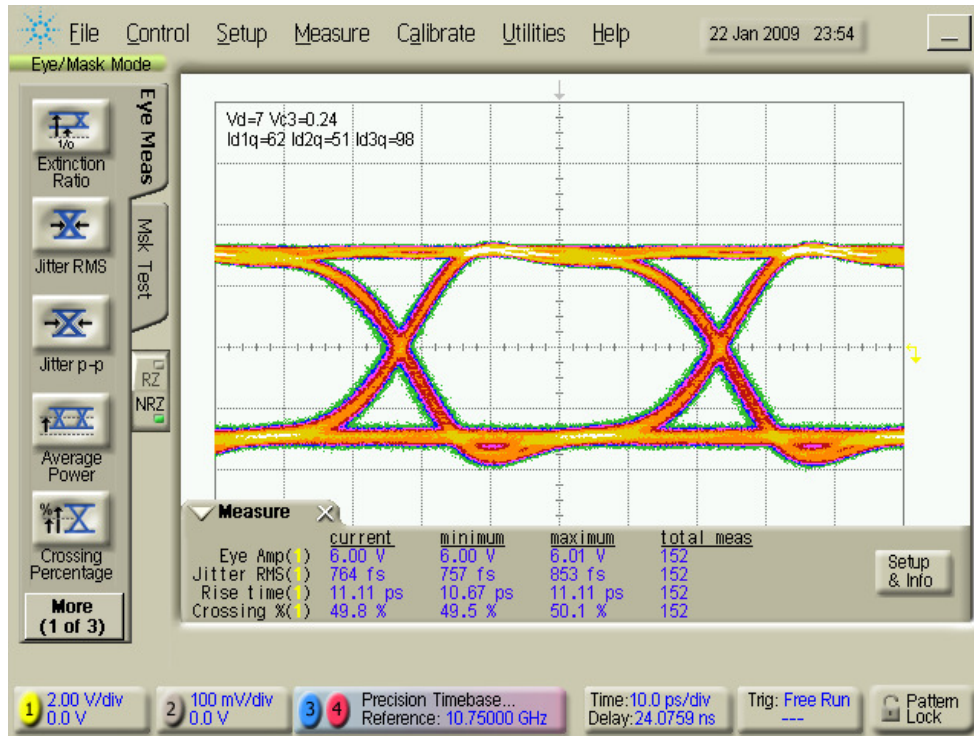
- 1/ Channel operating temperature will directly affect the device median lifetime (Tm). For maximum life, it is recommended that channel temperatures be maintained at the lowest possible levels.
- 2/ θ_{jc} is modeled based upon hottest stage (stage 3) because there is negligible thermal coupling between stages. It is the thermal resistance of the part calculated from the junction to the bottom of the TGA4943-SL package.

To calculate the temperature rise, calculate the dissipated power in the third stage ($P_{diss} = I_{dq3} * V_{d3}$) and multiply by θ_{jc} . For example: Tbase = 85 °C, Idq3 = 190 mA, Vd3 = 7V. $P_{diss_stage3} = 1.33 \text{ W}$. $\theta_{jc}=39.4 \text{ }^{\circ}\text{C/W}$. Temperature rise = $\theta_{jc} * P_{diss} = 52.4 \text{ }^{\circ}\text{C}$; Tchannel = Tbase + Temp rise = 137.4 °C

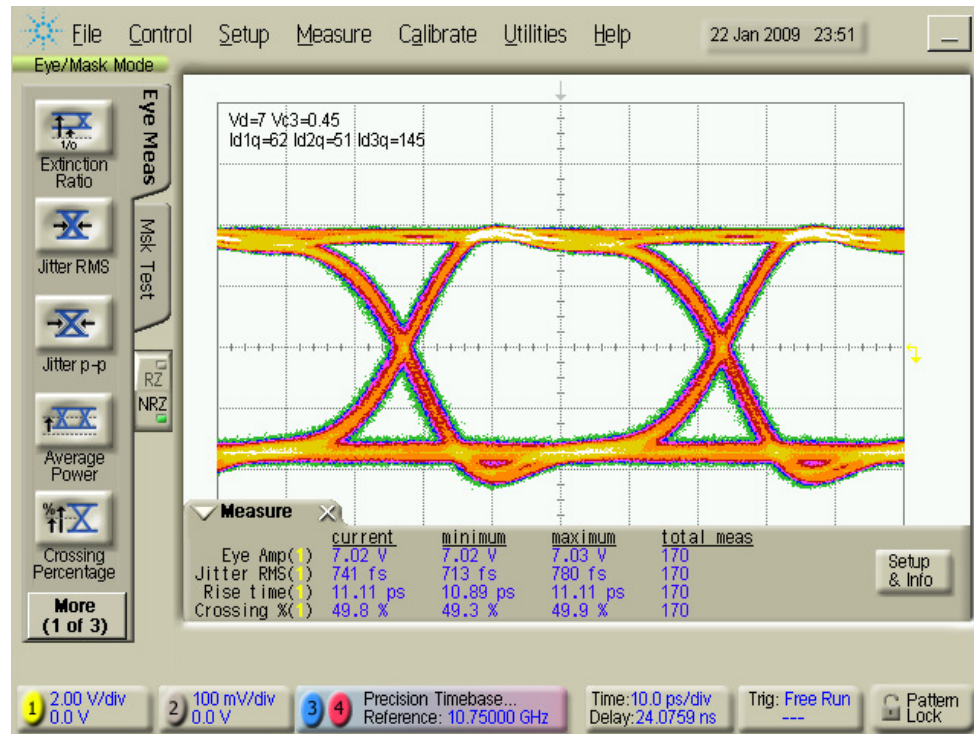
Median Lifetime (Tm) vs. Channel Temperature



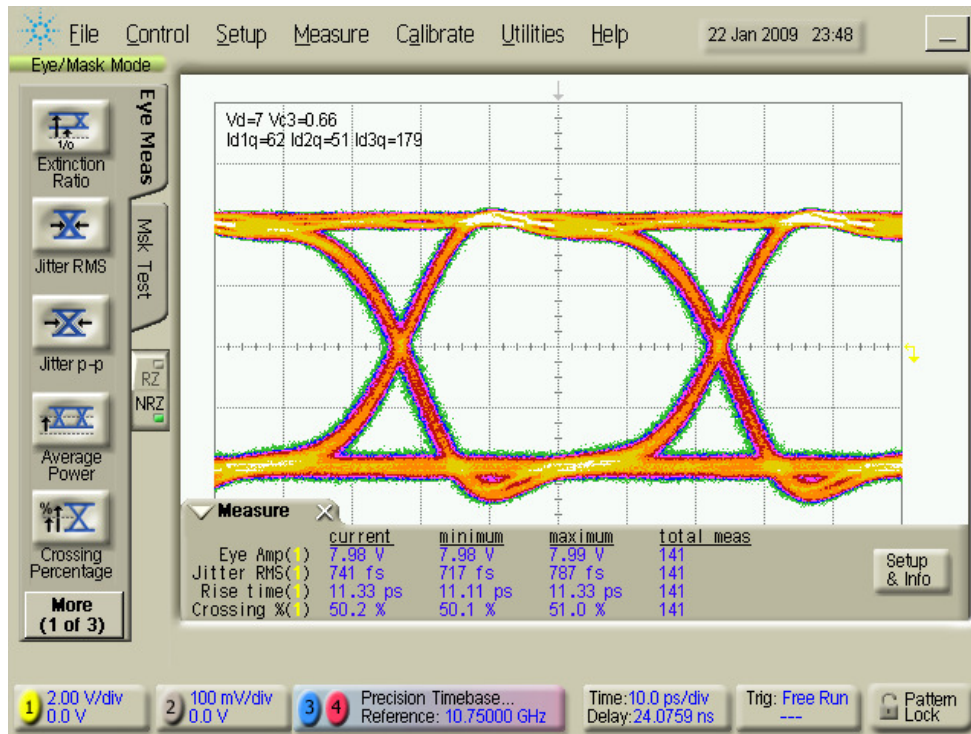
Vd = 7 V, Vin = 0.5 Vpp, Vout = 6 Vpp, 21.5 Gb/s, PRBS 2³¹ -1



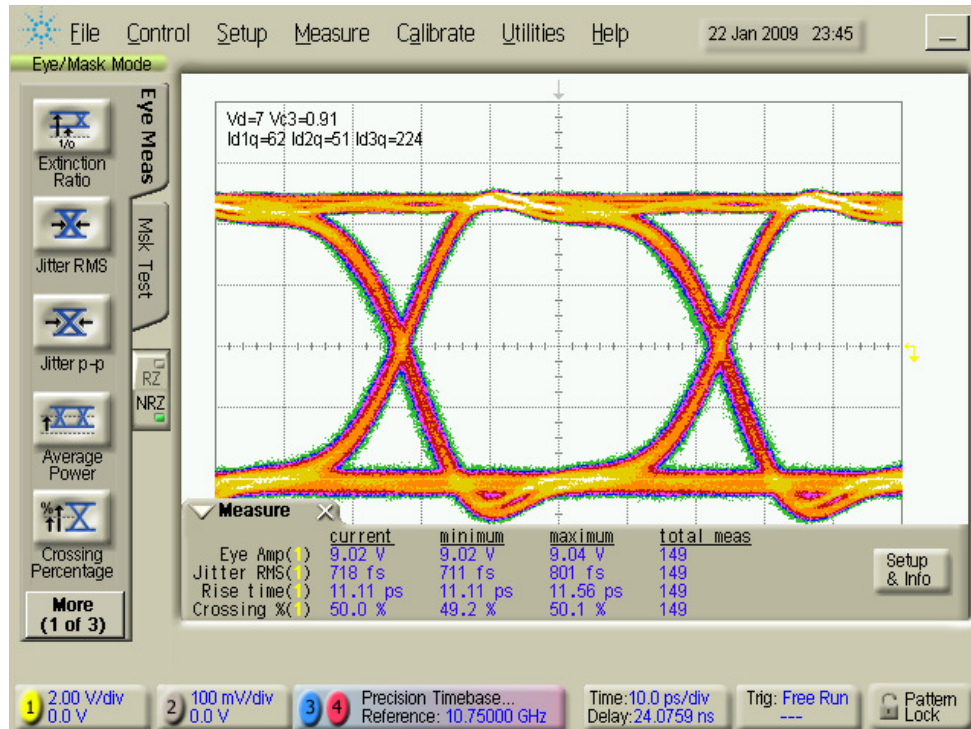
Vd = 7 V, Vin = 0.5 Vpp, Vout = 7 Vpp, 21.5 Gb/s, PRBS 2³¹ -1



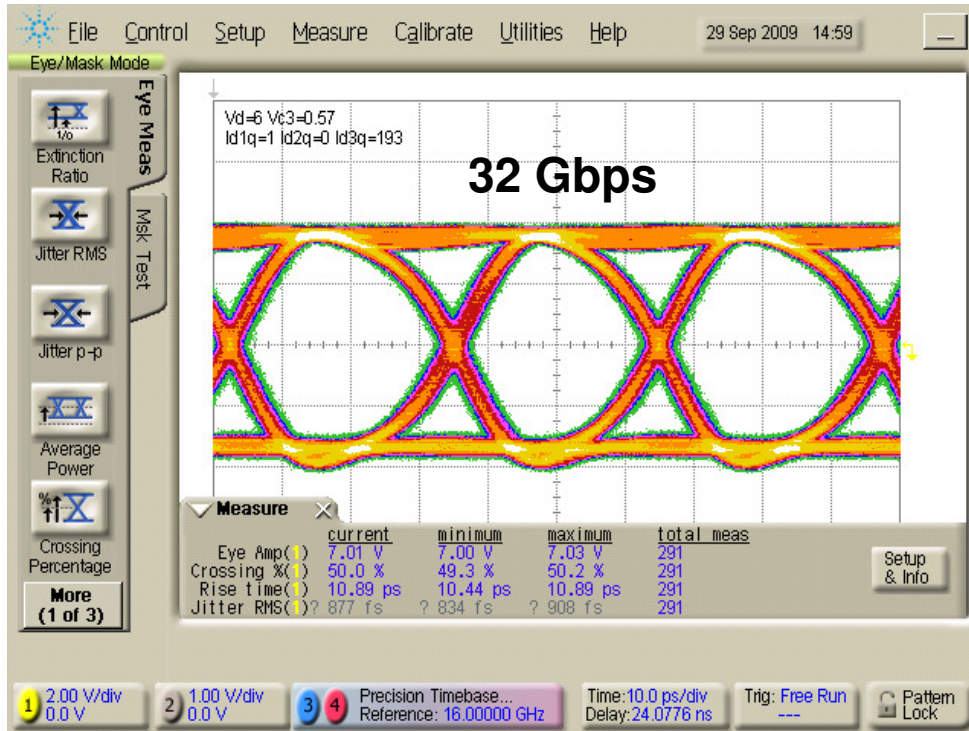
Vd = 7 V, Vin = 0.5 Vpp, Vout = 8 Vpp, 21.5 Gb/s, PRBS 2³¹ -1



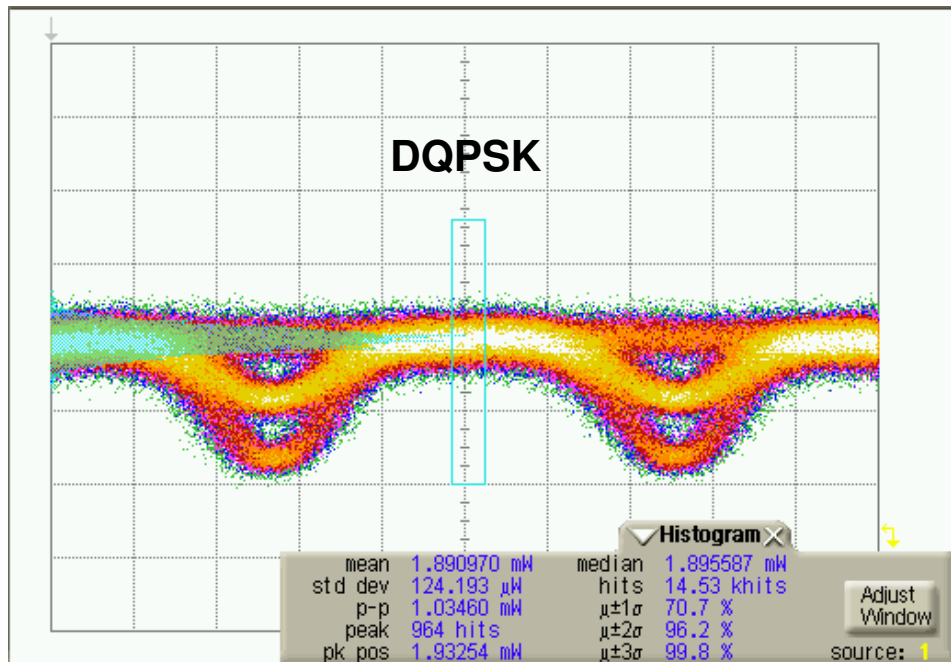
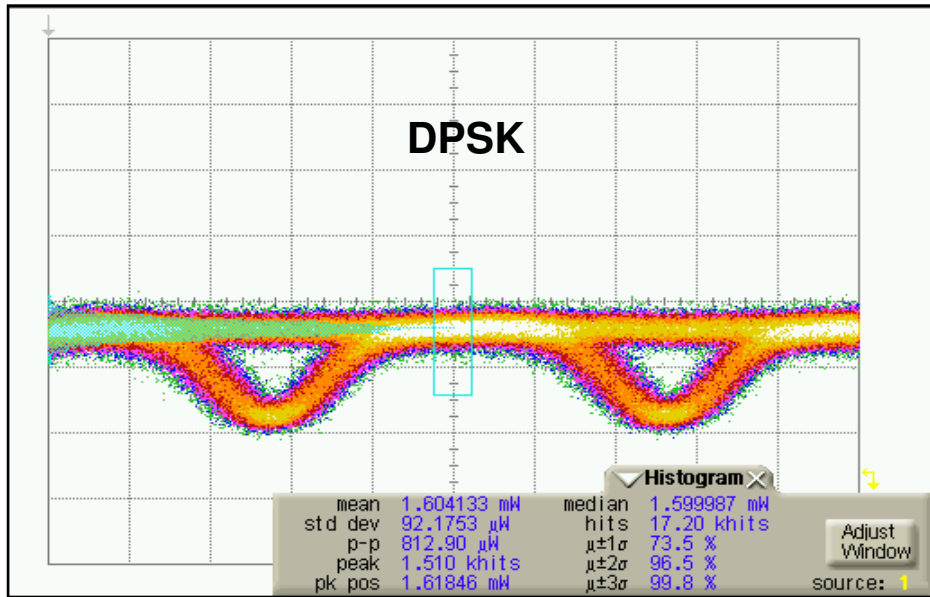
Vd = 7 V, Vin = 0.5 Vpp, Vout = 9 Vpp, 21.5 Gb/s, PRBS 2³¹ -1



Vd = 7 V, Vin = 0.5 Vpp, Vout = 10.6 Vpp, 32 Gb/s, PRBS 2³¹ -1

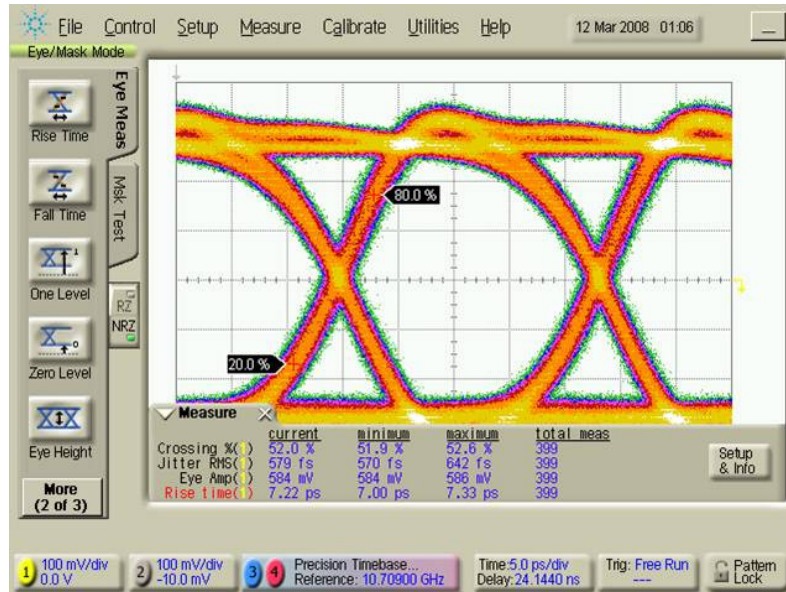


**Measured Data: $V_d = 7\text{ V}$, $V_{c1, 2, 3} = 0.7, 0.7, 0.8\text{ V}$,
 $I_{dq1, 2, 3} = 40, 60, 210\text{ mA}$,
 $V_{in} = 0.48\text{ Vpp}$, $V_{out} = 8\text{ Vpp}$, 22 Gb/s**



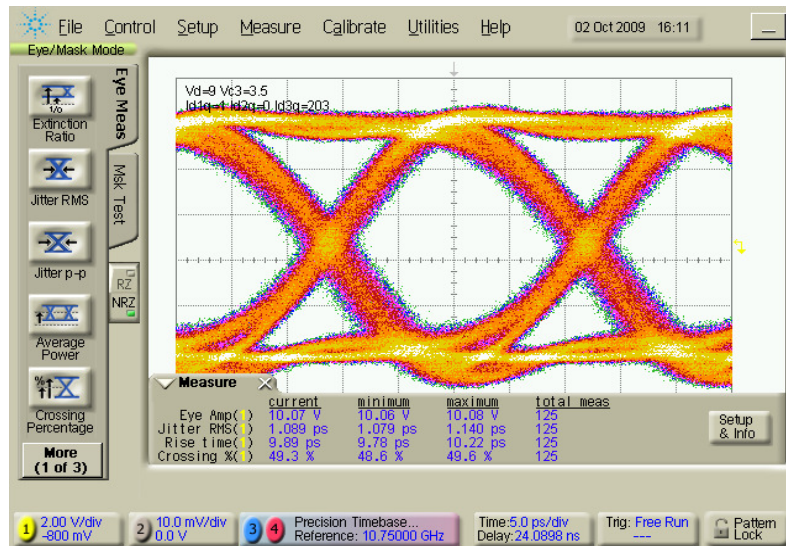
ODB Application Electrical Eye Performance: Input Eye**

Vout = 0.5 Vpp, 43 Gbps, PRBS 2^31 -1



ODB Application Electrical Eye Performance: Output Eye**

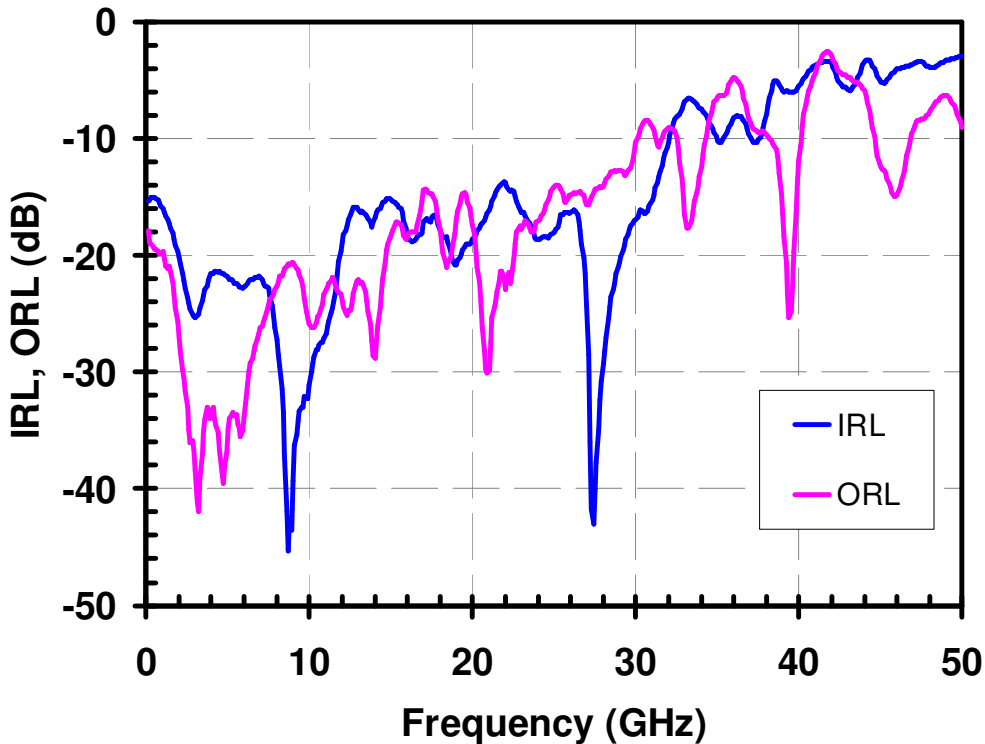
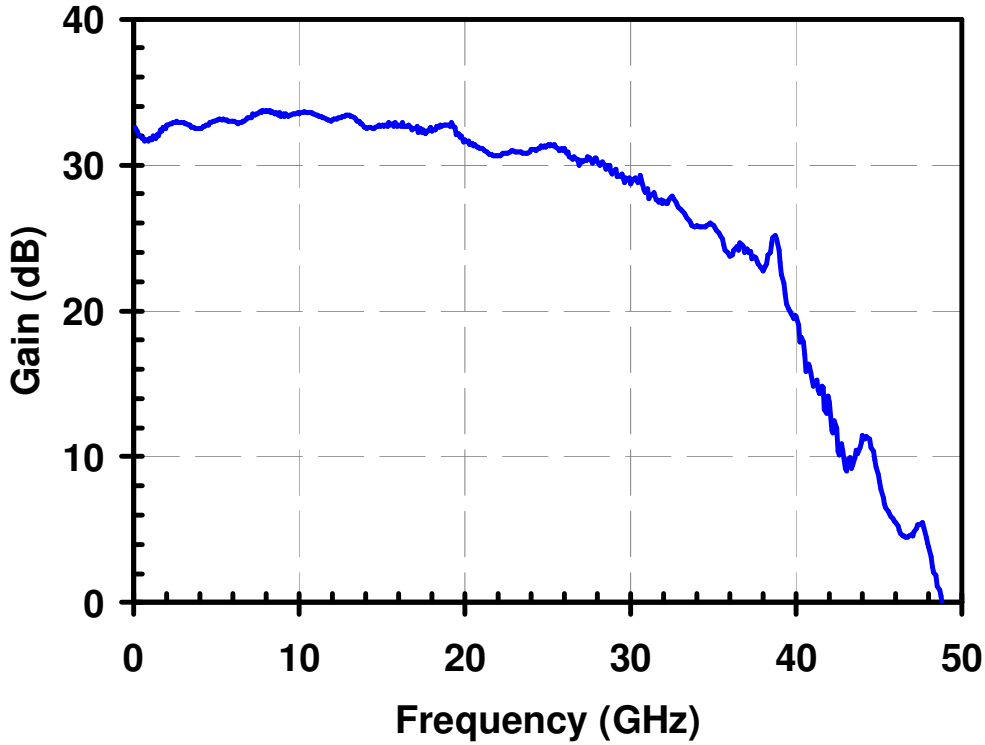
Bias conditions: Vd1,2,3 = 9 V, Idq = 332 mA, Vc1,2,3 = 0.7, 0.7, 3.5 V Typical



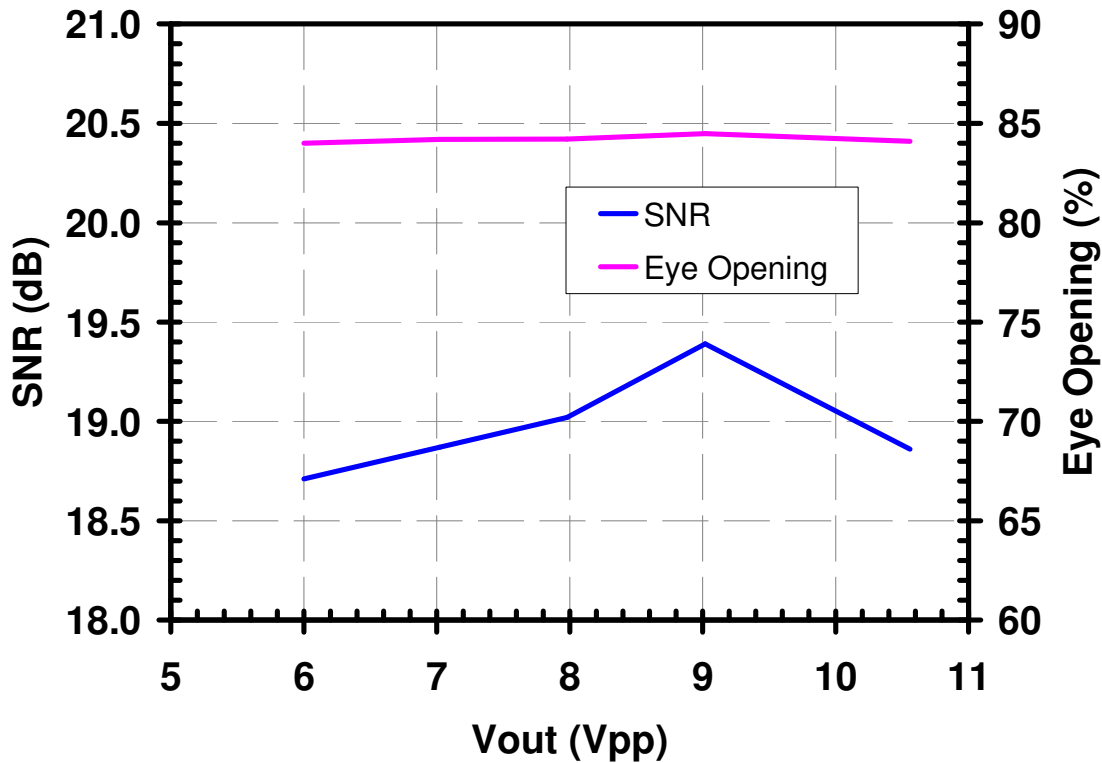
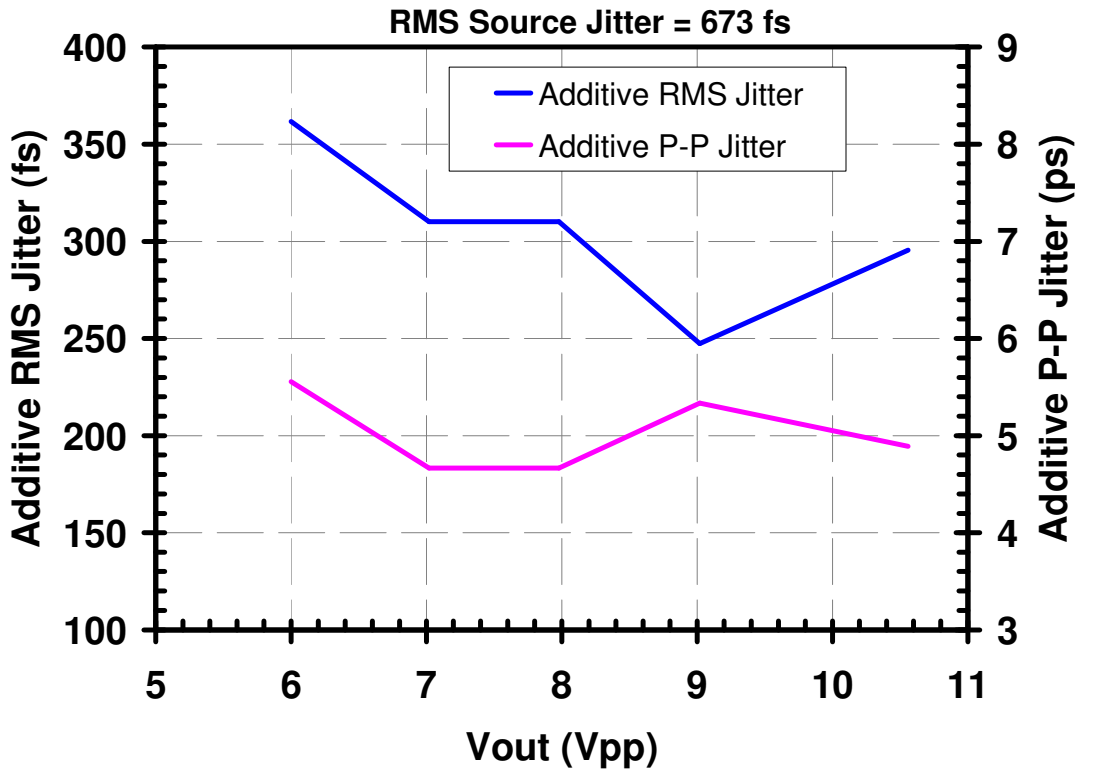
** Contact TriQuint Semiconductor for specific Application NOTE for ODB Application

Measured Data

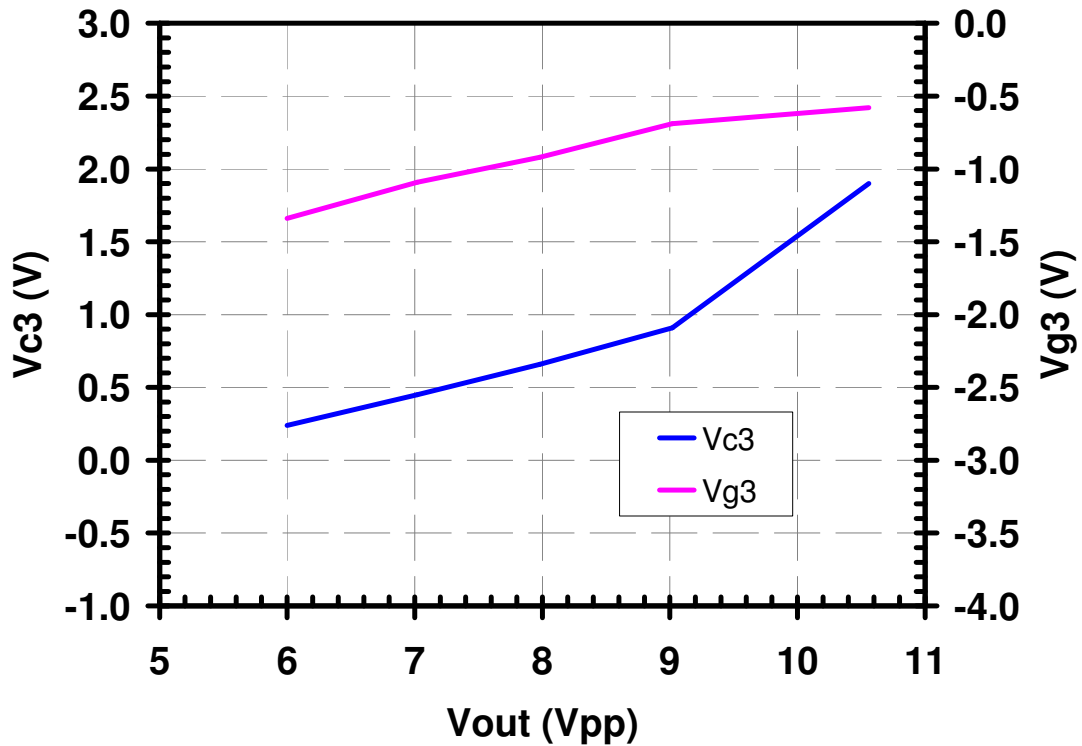
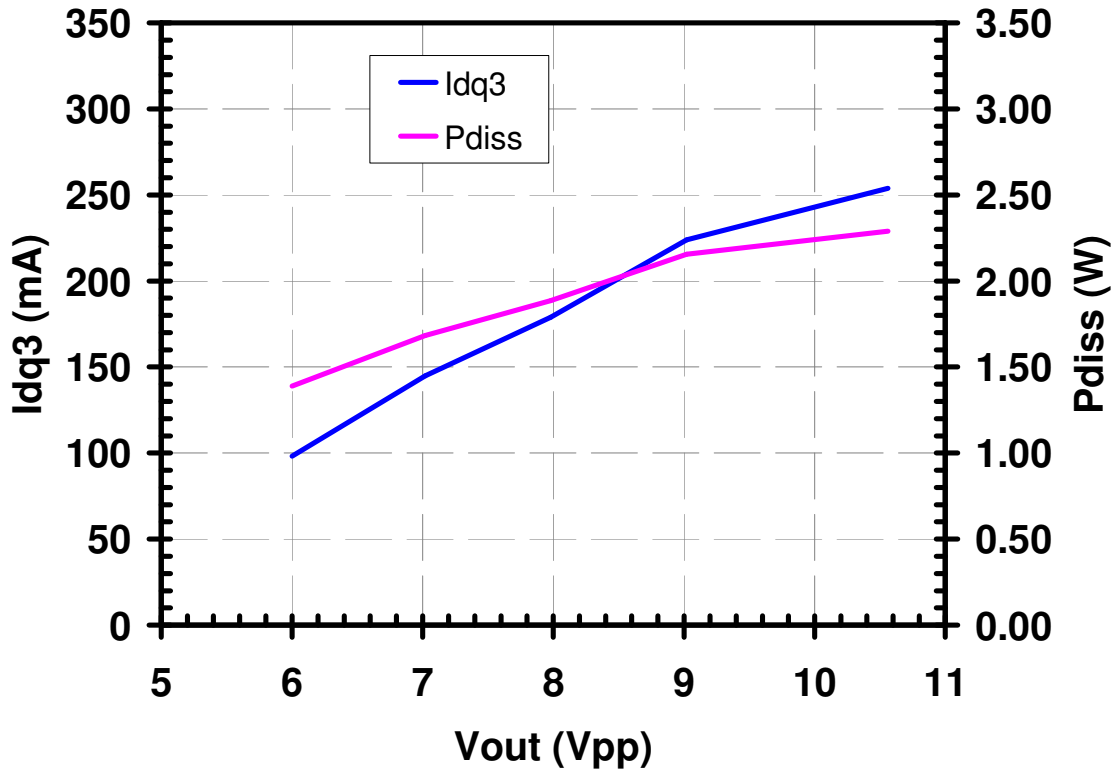
**Bias Conditions: $V_d = 7\text{ V}$, $I_{dq} = 293\text{ mA}$,
 $V_{g1,2,3} = -0.5, -1.7, -0.9\text{ V}$, $V_{c1,2,3} = 0.7, 0.7, 0.7\text{ V}$ Typical**



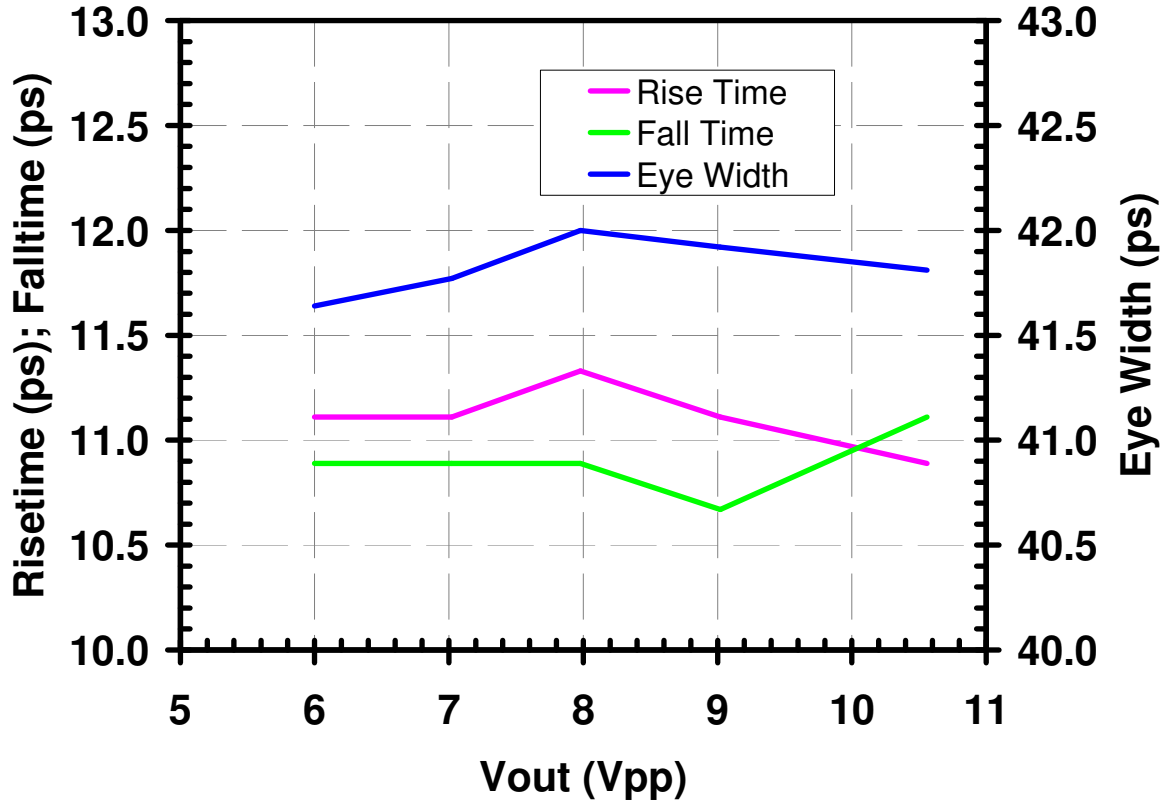
Measured Data: $V_{in} = 0.5 \text{ Vpp}$, 21.5 Gb/s , $V_d = 7\text{V}$



Measured Data: $V_{in} = 0.5 \text{ Vpp}$, 21.5 Gb/s , $V_d = 7 \text{ V}$



Measured Data: $V_{in} = 0.5 \text{ Vpp}$, 21.5 Gb/s , $V_d = 7 \text{ V}$



Environmental Ratings

Moisture Sensitivity Rating	ESD Rating
MSL5a	HBM Class > 200 V, CDM > 1000 V

Ordering Information

Part	Package Style
TGA4943-SL	Land Grid Array, Surface Mount (RoHS)